

Abstract**Method for manufacturing an electronic component and electronic component**

The present invention relates to the field of electrical engineering and concerns a method for manufacturing an electronic component with at least one electronic element (12) that is electrically connected to a segment (14.1) of a strip (4) made of a carrier material, wherein the strip (4) is rolled by rolling a base material, the surface (8) formed by rolling is removed to form a contact point (6) exposed on the strip, which is formed by the base material, the rolled strip (4) is wound into a coil (10), the rolled strip (4) is unwound from the coil (10) and the segment (14.1) is separated from the strip (4), and a wire (16) is bonded in an electrically conductive manner in the contact point (6) for the electrical connection of the electronic element (12). The invention also relates to an electronic component manufactured according to the method and a unit (18) ready for shipment comprising the coil (10), which has a contact point (6) exposed on the strip (4) for a wire, at which the surface (8) formed by rolling is removed and the base material of the coil (10) is exposed.

(Fig. 3)